The TLC2543-Q1 BoosterPack™ Plug-in Module (BOOSTXL-TLC2543) allows users to evaluate the functionality of Texas Instruments' TLC2543-Q1 SAR ADC. The TLC2543-Q1 is a 12-bit, 11-channel, automotive qualified SAR ADC. This user's guide describes both the hardware platform with an TLC2543-Q1 device and the graphical user interface (GUI) software used to configure the various modes of operation of this device.

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## 1 Introduction

The BOOSTXL-TLC2543 is a fully-assembled evaluation platform designed to highlight the TLC2543-Q1 device features and its various modes of operations.

The BOOSTXL-TLC2543 EVM interfaces to the TM4C1294 LaunchPad™ Development Kit (EK-TM4C1294XL). The Tiw C Series TM4C1294 MCU on the TM4C1294 LaunchPad Development Kit communicates with the TLC2543-Q1 through its SPI interface and acts as a USB-to-PC GUI communication bridge.

**NOTE:** The BOOSTXL-TLC2543 requires an external master controller to evaluate the TLC2543-Q1.

The TM4C1294 LaunchPad Development Kit is controlled by commands received from the BOOSTXL-TLC2543 EVM GUI, and the kit returns the data to the GUI for display and analysis. If the TM4C1294 LaunchPad Development Kit is not used, the BoosterPack™ Plug-in Module format of the BOOSTXL-TLC2543 board allows an alternative external host to communicate with the TLC2543-Q1.

The BOOSTXL-TLC2543 EVM incorporates all required circuitry and components with the following features:

- The TLC2543-Q1 12-bit, 11-channel, automotive qualified SAR ADC with SPI interface
- The REF5045A optional low power voltage reference to generate a 4.5-V reference for the TLC2543-Q1 VREF pin when using 5.0 V from TM4C1294 LaunchPad Development Kit
- The OPA2320 optional precision, low noise, dual operational amplifier to generate buffered input for the TLC2543-Q1 AIN0 and AIN1 pins
- The TPS79901 optional adjustable linear regulator to generate stable 5V output voltage to power the TLC2543-Q1 VCC pin when using the USB power from the TM4C1294 LaunchPad Development Kit
- SPI interface for communication and configuration of modes available on the TLC2543-Q1

Figure 1 shows the BOOSTXL-TLC2543 EVM architecture along with the key components and blocks listed in the features.

![Figure 1. BOOSTXL-TLC2543 EVM Block Diagram](image.png)
Section 2 lists various onboard components that are used to interface analog input, digital interface, and provide power supply to BOOSTXL-TLC2543 EVM. Figure 2 shows a BOOSTXL-TLC2543 EVM overview.

![Figure 2. BOOSTXL-TLC2543EVM Top Level Overview](image)

### 2.1 Connectors for Analog Input

The BOOSTXL-TLC2543 EVM is designed for easy interface-to-analog sources through a 100-mil header. Connector J10 allows analog source connectivity. Table 1 lists the analog input connector and input channel configuration.

<table>
<thead>
<tr>
<th>J10 Connector Pin</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>J10:1</td>
<td>Analog input for channel 0 of ADC</td>
</tr>
<tr>
<td>J10:2</td>
<td>Analog input for channel 1 of ADC</td>
</tr>
<tr>
<td>J10:3</td>
<td>Analog input for channel 2 of ADC</td>
</tr>
<tr>
<td>J10:4</td>
<td>Analog input for channel 3 of ADC</td>
</tr>
<tr>
<td>J10:5 and J10:6</td>
<td>BoosterPack™ Plug-in Module ground</td>
</tr>
<tr>
<td>J10:7</td>
<td>Analog input for channel 4 of ADC</td>
</tr>
<tr>
<td>J10:8</td>
<td>Analog input for channel 5 of ADC</td>
</tr>
<tr>
<td>J10:9</td>
<td>Analog input for channel 6 of ADC</td>
</tr>
<tr>
<td>J10:10</td>
<td>Analog input for channel 7 of ADC</td>
</tr>
<tr>
<td>J10:11</td>
<td>Analog input for channel 8 of ADC</td>
</tr>
</tbody>
</table>
Table 1. Input Connector and Channel Configuration (continued)

<table>
<thead>
<tr>
<th>J10 Connector Pin</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>J10:12</td>
<td>Analog input for channel 9 of ADC</td>
</tr>
<tr>
<td>J10:13</td>
<td>Analog input for channel 10 of ADC</td>
</tr>
<tr>
<td>J10:15 and J10:16</td>
<td>BoosterPack™ Plug-in Module ground</td>
</tr>
<tr>
<td>J10:14, 17, 18, 19, 20</td>
<td>No Connection</td>
</tr>
</tbody>
</table>

The analog input range is from GND to $+V_{REF}$. A maximum of 11 single-ended inputs may be applied to J10 using pins J10:1 to J10:4 and J10:7 to J10:13.

The user can configure the input to channel 0 to use the OPA2320 buffer through a 100-$\Omega$ resistor with an 1000-pF capacitor to GND. Jumper J7 can be placed on pins 1-2 to select this unity gain buffer configuration of the OPA2320. In this case, the channel 0 input is provided through the SMA connector J8. The user can also place Jumper J12 on pins 1-2 to create a similar configuration for a channel 1 input provided through the SMA connector J13.

2.2 Voltage Reference

The BOOSTXL-TLC2543 EVM has two sources for the reference voltage. Jumper J11 can select the VREF voltage from either the REF5045A ($U_9$) or from 5-V VCC. The EVM is factory-configured for use with the REF5045A 4.5-V reference (J11 pins 2-3).

2.3 Digital Interface

As noted in Section 1, the BOOSTXL-TLC2543 EVM interfaces with the TM4C1294 LaunchPad Development Kit, which in turn communicates with the computer over USB. The two devices on the booster pack that the TM4C1294 communicates with are the TLC2543-Q1 ADC (over SPI) and the EEPROM (over I\textsuperscript{2}C). The EEPROM comes preprogrammed with the information required to configure and initialize the BOOSTXL-TLC2543 EVM platform every time on power up.

2.4 BOOSTXL-TLC2543 Digital I/O Interface

The BOOSTXL-TLC2543 EVM supports the SPI digital interface and functional modes as detailed in the TLC2543-Q1 data sheet. The TM4C1294 LaunchPad Development Kit is operating at a 3.3-V logic level and is connected to the 5-V digital I/O lines of the ADC through level shifters (SN74LVC1T45QDCURQ1 and SN74LVC2T45QDCURQ1).

2.5 Power Supply

The device supports a single power supply with a wide range of operation. The VCC can operate from 2.7 V to 5 V. The available onboard TPS79901 adjustable voltage regulator is configured to supply 5 V to the TLC2543-Q1 VCC pin on the BOOSTXL-TLC2543 EVM.
3 BOOSTXL-TLC2543 EVM Setup

3.1 BOOSTXL-TLC2543 EVM Graphical User Interface Software Installation

The following steps describe the BOOSTXL-TLC2543 EVM GUI software installation:

1. Download the latest version of the EVM graphical user interface (GUI) installer from the Tools and Software folder of the device, and run the GUI installer to install the EVM GUI software on your windows PC.

2. Accept the License Agreements and follow the on-screen instructions to complete the installation (see Figure 3).

![License Agreement](image)

Figure 3. BOOSTXL-TLC2543 EVM GUI Installation
3. Click the *Next* button when the *Device Driver Installation Wizard* prompt appears on the screen to start the installation process (see Figure 4). Click the *Finish* button when the install is complete.

![Device Driver Installation Wizard](image-url)

*Figure 4. BOOSTXL-TLC2543 EVM Driver Installation*
4. Open the computer’s “Device Manager”. You must be able to see the “Stellaris Virtual Serial Port” and “Stellaris In-Circuit Debug Interface” as shown in Figure 5.

Figure 5. TM4C1294 LaunchPad™ Development Kit Stellaris Virtual Serial Port and ICDI Driver
3.2 LM Flash Programmer for TM4C1294 LaunchPad™ Development Kit Software Programming

The TM4C1294 LaunchPad Development Kit ships with a default firmware program flashed on its memory. When a TM4C1294 LaunchPad Development Kit is connected to the PC for the first time, its firmware needs to be updated for communications with the BOOSTXL-TLC2543 EVM. The following steps describe the programming of this firmware on the flash memory:

1. Download the latest version of LM Flash Programmer. The LM Flash Programmer is also included as part of the BOOSTXL-TLC2543 EVM GUI installation in the following folder: C:\Program Files (x86)\Texas Instruments\TLC2543\Firmware

2. Make sure the power select JP1 jumper on the TM4C1294 LaunchPad Development Kit is on ICDI. Connect the Debug USB port on the TM4C1294 LaunchPad Development Kit to the PC with a micro USB cable as shown in Figure 6. This must light the green power LED D0 on the TM4C1294 LaunchPad Development Kit.

Figure 6. TM4C1294 LaunchPad™ Development Kit Software Programming Setup
3. Launch the LM Flash Programmer. In the Configuration tab select **TM4C1294XL LaunchPad** from the drop-down menu as shown in Figure 7.

![Figure 7. TM4C1294 LaunchPad™ Development Kit Selection in Configuration Tab](image-url)
4. Program the TM4C1294 with the BOOSTXL-TLC2543 EVM firmware from the Program tab as shown in Figure 8.

![LM Flash Programmer - Build 1613](image)

Figure 8. TM4C1294 LaunchPad™ Development Kit Programming Using LM Flash Programmer

5. Disconnect the micro USB cable from the TM4C1294 LaunchPad Development Kit debug port after programming and verification is successful. Switch the power select JP1 jumper position from ICDI to the OTG location.
3.3  **BOOSTXL-TLC2543 EVM Stack Up**

The following steps are the instructions to set up the BOOSTXL-TLC2543 EVM for evaluation:

1. Stack the BOOSTXL-TLC2543 EVM on the TM4C1294 LaunchPad Development Kit. Make sure the 20-pin connector (J1, J3) on BOOSTXL-TLC2543 EVM is mapped against connector X6 and connector (J4, J2), and that the BOOSTXL-TLC2543 EVM is mapped against connector X7 on the TM4C1294 LaunchPad Development Kit. Pin 1 of BOOSTXL-TLC2543 EVM must align with pin 1 of connector X6 on the TM4C1294 LaunchPad Development Kit.

2. Position the power select JP1 jumper on the TM4C1294 LaunchPad Development Kit on pins that correspond to the OTG.

3. Connect the TM4C1294 LaunchPad Development Kit USB port U7 to the PC with the micro USB cable. This must light the green power LED D0 on the TM4C1294 Development Kit.

4. Open computer's "Device Manager". You must see under ports “VIA USB BoosterPack” and “VIA USB BoosterPack Console” as shown in Figure 9.

![Device Manager]

**Figure 9. TM4C1294 LaunchPad™ Development Kit VIA BoosterPack™ Plug-in Module Driver**
5. **Figure 10** shows the assembled BOOSTXL-TLC2543 EVM and TM4C1294 LaunchPad Development Kit configuration.

![Figure 10. BOOSTXL-TLC2543 EVM stacked on TM4C1294 LaunchPad™ Development Kit](image-url)
4 BOOSTXL-TLC2543 EVM GUI Operation

4.1 Description

Figure 11 shows the landing page of the BOOSTXL-TLC2543 EVM GUI. This page provides a high-level overview of the TLC2543-Q1 device. The left corner shows the tabs required to navigate to the BOOSTXL-TLC2543 EVM GUI Home and Analysis pages. When the TM4C1294 LaunchPad Development Kit with the stacked BOOSTXL-TLC254 EVM is connected to the PC with the micro USB cable, the GUI reads the onboard EEPROM to detect the BoosterPack Plug-in Module. Once the BoosterPack Plug-in Module is detected and connected, the GUI indicates this status at the bottom left corner of the GUI.

Figure 11. BOOSTXL-TLC2543 GUI Landing Page
4.2 Time Domain Analysis

Go to Analysis page, and select the Time Domain Analysis. Time Domain Analysis displays the acquired data versus time for the selected channel as shown in Figure 12. Note default reference voltage for ADC measurement REF Volt (V) is set as 4.5 V.

4.2.1 Measure AIN0 (Channel0) Voltage

This section describes the steps involved in selecting and measuring AIN0 (Channel0) voltage:
1. Make sure following shunt is in place on the BOOSTXL-TLC2543 EVM: J11 between 2 and 3 (select VREF = 4.5 V)
2. Connect J10.1 to J1.1 (3.3 V) by a jumper wire.
3. Select “Samples” as 4096, set “SCLK” as 1000 (KHz), and set “Sample Rate” as 10 (KHz).
4. Make sure "Selected Channel" is Channel0 as shown in Figure 12 below.
5. Press “Collect”.
6. Make sure the Min Code, Max Code, Min Volt (V), and Max Volt (V) read outs are shown. See Figure 12 for an example.

![Figure 12. AIN0 (Channel0) Voltage](image-url)
4.3 Frequency Domain Analysis

The Frequency Domain page in the GUI performs the fast fourier transform (FFT) of the captured data and shows the resulting frequency domain plots of the selected channel of TLC2543-Q1. This page also calculates key ADC dynamic performance parameters, such as signal-to-noise ratio (SNR), total harmonic distortion (THD), signal-to-noise and distortion ratio (SINAD), spurious-free dynamic range (SFDR), and effective number of bits (ENOB). Figure 13 shows the Frequency Domain analysis display for a 2-kHz sinusoidal input generated by PSIEVM.

Figure 13. Frequency Domain Analysis Page
4.3.1 FFT Analysis Settings and Controls

Sample Rate - This field indicates the sampling frequency of the ADC data (kHz)

Samples - The FFT requires a time domain record with a number of samples that is a power of 2. The Samples drop-down menu provides a list of values that satisfy this requirement.

Fund Freq (kHz) - This field displays the frequency of the largest amplitude input signal computed from the FFT data, typically the fundamental frequency.

Window - The window function is a mathematical function that reduces the signal to zero at the end points of the data block.

In applications where coherent sampling cannot be achieved, a window-weighing function can be applied to the data to minimize spectral leakage. The following options are available:

- Rectangular
- Hamming
- Hann
- Blackman
- 7-Term Blackman-Harris

For a more thorough discussion of windowing, refer to IEEE1241-2000

Harmonics - This field sets the number of harmonics that are included in the FFT performance calculations.

4.4 Histogram Analysis

The Histogram Analysis page creates a histogram of the captured channel data and displays it. A histogram is merely a count of the number of times a code has occurred in a particular data set. The following parameters of the captured data set are displayed:

- The Std Dev \( \sigma \) displays the standard deviation of the data set. This value is equivalent to the RMS noise of the signal when analyzing a dc data set.
- The Mean displays the average value of the data set.
- The Median displays the median value of the data set.
- The Code Spread displays the peak-to-peak spread of the codes in the data set; for a dc data set, this range would be the peak-to-peak noise.
5 Bill of Materials, Printed-Circuit Board Layout, and Schematics

This section contains the BOOSTXL-TLC2543 EVM bill of materials (BOM), printed-circuit board (PCB) layout, and schematics.

5.1 Bill of Materials

Table 2 lists the bill of materials (BOM) for the BOOSTXL-TLC2543 EVM.

<table>
<thead>
<tr>
<th>Designator</th>
<th>Quantity</th>
<th>Description</th>
<th>Manufacturer Part Number</th>
<th>Manufacturer</th>
</tr>
</thead>
<tbody>
<tr>
<td>PCB</td>
<td>1</td>
<td>Printed Circuit Board</td>
<td>DC012</td>
<td>Any</td>
</tr>
<tr>
<td>C1, C4, C5</td>
<td>3</td>
<td>CAP, CERM, 2.2 µF, 16 V, +/- 10%, X7R, 0805</td>
<td>C0805C225K4RACTU</td>
<td>Kemet</td>
</tr>
<tr>
<td>C3</td>
<td>1</td>
<td>CAP, CERM, 180 pF, 50 V, +/- 1%, C0G/NP0, 0402</td>
<td>04025A181FAT2A</td>
<td>AVX</td>
</tr>
<tr>
<td>C6</td>
<td>1</td>
<td>CAP, CERM, 10 µF, 16 V, +/- 20%, X5R, 0805</td>
<td>0805YD106MAT2A</td>
<td>AVX</td>
</tr>
<tr>
<td>C7, C16, C23, C27, C28, C29</td>
<td>6</td>
<td>CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603</td>
<td>C0603C105K3RACTU</td>
<td>Kemet</td>
</tr>
<tr>
<td>C9, C10, C12, C13, C17, C19, C21</td>
<td>7</td>
<td>CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0603</td>
<td>GRM188R71C103KA01D</td>
<td>Murata</td>
</tr>
<tr>
<td>C11, C15</td>
<td>2</td>
<td>CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0603</td>
<td>GRM188R71C104KA01D</td>
<td>Murata</td>
</tr>
<tr>
<td>C18, C30</td>
<td>2</td>
<td>CAP, CERM, 1000 pF, 50 V, +/- 5%, C0G/NP0, 0603</td>
<td>C0603C102J5GACTU</td>
<td>Kemet</td>
</tr>
<tr>
<td>C22, C25</td>
<td>2</td>
<td>CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0603</td>
<td>0603D104KAT2A</td>
<td>AVX</td>
</tr>
<tr>
<td>C26</td>
<td>1</td>
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<td>C2012X5R1E106K125AB</td>
<td>TDK</td>
</tr>
<tr>
<td>C31</td>
<td>1</td>
<td>CAP, TA, 10 µF, 10 V, +/- 20%, 3 ohm, SMD</td>
<td>TAJA106M010RNJ</td>
<td>AVX</td>
</tr>
<tr>
<td>J1/J3, J2/J4</td>
<td>2</td>
<td>Receptacle, 2.54mm, 10x2, Tin, TH</td>
<td>SSQ-110-03-T-D</td>
<td>Samtec</td>
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<td>J5, J7, J12</td>
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<td>Header, 100mil, 2x1, Tin, TH</td>
<td>PEC02SAAN</td>
<td>Sullins Connector Solutions</td>
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<td>Header, 100mil, 3x1, Tin, TH</td>
<td>PEC03SAAN</td>
<td>Sullins Connector Solutions</td>
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<td>R1, R3, R5, R6, R7, R8, R9, R15, R19, R28, R30</td>
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<td>RES, 0.1%, 0.1 W, 0603</td>
<td>CRCW06030000Z0EA</td>
<td>Vishay-Dale</td>
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<td>R2</td>
<td>1</td>
<td>RES, 0.1%, 0.1 W, 0603</td>
<td>RC0603FR-0710RL</td>
<td>Yageo America</td>
</tr>
<tr>
<td>R4</td>
<td>1</td>
<td>RES, 10 k, 0.1%, 0.063 W, 0402</td>
<td>RG1005P-104-B-T5</td>
<td>Susumu Co Ltd</td>
</tr>
<tr>
<td>R10</td>
<td>1</td>
<td>RES, 31.6 k, 1%, 0.063 W, 0402</td>
<td>CRCW040231K6FKED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R11, R14</td>
<td>2</td>
<td>RES, 10 k, 1%, 0.063 W, 0402</td>
<td>CRCW040210K0FKED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R12, R13</td>
<td>2</td>
<td>RES, 100 k, 0.1%, 0.0625 W, 0402</td>
<td>RC0402FR-071K</td>
<td>Yageo America</td>
</tr>
<tr>
<td>R16, R26</td>
<td>2</td>
<td>RES, 100 k, 5%, 0.063 W, 0402</td>
<td>CRCW0402100KJNED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R18, R29</td>
<td>2</td>
<td>RES, 100 k, 1%, 0.063 W, 0402</td>
<td>CRCW0402100RFKED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R20, R31</td>
<td>2</td>
<td>RES, 1.0 M, 5%, 0.063 W, 0402</td>
<td>CRCW0402100M0JNED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R21, R22, R23, R24</td>
<td>4</td>
<td>RES, 49.9, 1%, 0.063 W, 0402</td>
<td>RC0402FR-0749R9L</td>
<td>Yageo America</td>
</tr>
<tr>
<td>SH-J1</td>
<td>1</td>
<td>Shunt, 100mil, Gold plated, Black</td>
<td>382811-6</td>
<td>AMP</td>
</tr>
<tr>
<td>TP4, TP5, TP6, TP7</td>
<td>4</td>
<td>Test Point, Miniature, Black, TH</td>
<td>5001</td>
<td>Keystone</td>
</tr>
<tr>
<td>U1</td>
<td>1</td>
<td>5.5 V, Buck-Boost Charge Pump Regulator, 60 mA, 3 to 5.5 V Input, -40 to 85 degC, 6-pin SOT23 (DDC6), Green (RoHS &amp; no Sb/Br)</td>
<td>REG71055IDDRCRQ1</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>U2</td>
<td>1</td>
<td>Single Output High PSRR LDO, 200 mA, Adjustable 1.2 to 6.5 V Output, 2.7 to 6.5 V Input, with Low IQ, 6-pin SOJ (DRV), -40 to 125 degC, Green (RoHS &amp; no Sb/Br)</td>
<td>TPS79901QDVRVRQ1</td>
<td>Texas Instruments</td>
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<td>U3, U6</td>
<td>2</td>
<td>Automotive Catalog Dual-Bit Dual Supply Transceiver with Configurable Voltage Translation, DDU0008A</td>
<td>SN74LVC2T45OCDURQ1</td>
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<td>I2C BUS EEPROM (2-Wire), TSSOP-8</td>
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<td>Rohm</td>
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<td>U5</td>
<td>1</td>
<td>Automotive Catalog Single-Bit Dual-Supply Bus Transceiver with Configurable Voltage Translation and, DCK0006A</td>
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<td>Texas Instruments</td>
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<td>Automotive, Precision, 20MHz, 0.9µA, RRIO, CMOS Operational Amplifier, DGK0008A (VSSOP-8)</td>
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<td>Texas Instruments</td>
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Table 2. Bill of Materials (continued)

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<td>TLC2543IDBRQ1</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>U9</td>
<td>1</td>
<td>Automotive Catalog, Low Noise, Very Low Drift, Precision Voltage Reference, -40 to 125 degC, 8-pin SOIC (D), Green (RoHS &amp; no Sb/Br)</td>
<td>REF5045AQDRQ1</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>C8, C14, C20, C24, C32</td>
<td>0</td>
<td>CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0603</td>
<td>GRM188R71C103KA01D</td>
<td>Murata</td>
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<td>J6, J9, J14</td>
<td>0</td>
<td>Header, 100mil, 2x1, Tin, TH</td>
<td>PEC02SAAN</td>
<td>Sullins Connector Solutions</td>
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<tr>
<td>J8, J13</td>
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<td>SMA Straight PCB Socket Die Cast, 50 Ohm, TH</td>
<td>S-1814832-1</td>
<td>TE Connectivity</td>
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<td>R17, R27</td>
<td>0</td>
<td>RES, 1.0 k, 5%, 0.063 W, 0402</td>
<td>CRCW04021K00JNED</td>
<td>Vishay-Dale</td>
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<td>R25, R32</td>
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<td>RES, 330 k, 5%, 0.063 W, 0402</td>
<td>CRCW0402330KJNED</td>
<td>Vishay-Dale</td>
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<td>0</td>
<td>Test Point, Multipurpose, Black, TH</td>
<td>5011</td>
<td>Keystone</td>
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</table>

5.2 PCB Layout

Figure 14 to Figure 17 show the EVM PCB layout.

Figure 14. BOOSTXL-TLC2543 Top Layer Routing
Figure 15. BOOSTXL-TLC2543 Ground Layer
Figure 16. BOOSTXL-TLC2543 Power Layer
Figure 17. BOOSTXL-TLC2543 Bottom Layer Routing
Figure 18. BOOSTXL-TLC2543 EVM Schematic Diagram
STANDARD TERMS FOR EVALUATION MODULES

1. **Delivery:** TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an “EVM” or “EVMs”) to the User (“User”) in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.

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1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.

2 **Limited Warranty and Related Remedies/Disclaimers:**

2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.

2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.

2.3 TI’s sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

3 **Regulatory Notices:**

3.1 United States

3.1.1 Notice applicable to EVMs not FCC-Approved:

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

**CAUTION**

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

**FCC Interference Statement for Class A EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*
FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:
This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:
(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:
Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:
Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables
Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lds/it_ia/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lds/it_ia/general/eStore/notice_01.page

3.3.2 Notice for Users of EVMs Considered “Radio Frequency Products” in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry’s Rule for Enforcement of Radio Law of Japan.
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or EVMs.
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.
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1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

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日本テキサス·インスツルメンツ株式会社
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西新宿三井ビル

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3.4 European Union
3.4.1 For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):
This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

4 EVM Use Restrictions and Warnings:
4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
4.3 Safety-Related Warnings and Restrictions:
4.3.1 User shall operate the EVM within TI’s recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
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